

Ordering number : \*EN5572

CMOS LSI



# LC897194

## CD-ROM Decoder with Built-In ATAPI (IDE) and DVD ECC Interfaces

### Preliminary

#### Overview

The LC897194 provides CD-ROM functionality and includes built-in DVD ECC and ATAPI (IDE) interfaces.

#### Function

- CD-ROM ECC functionality, an ATAPI (IDE) interface (the register and other blocks), and a DVD ECC interface

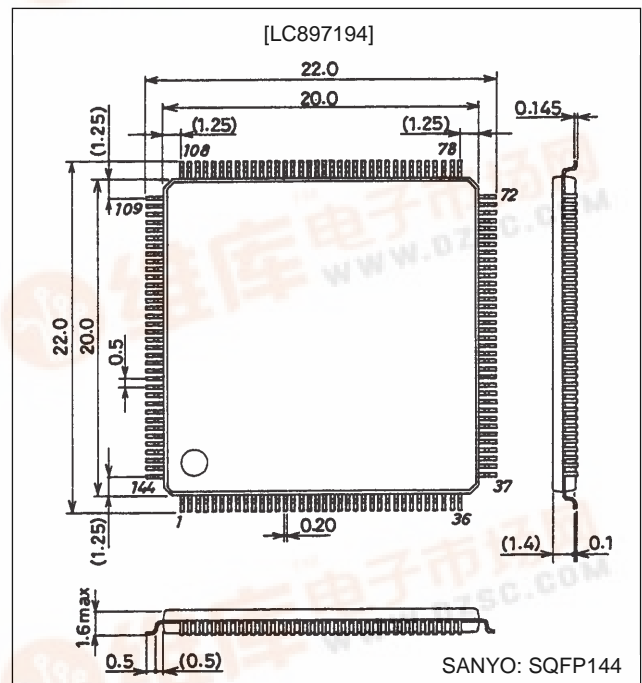
#### Features

- ATAPI (IDE) interface
- DVD ECC interface
- Supports up to 12x-speed playback (when using 70-ns 16-bit data path DRAM)
- Transfer rate: 16.6 MB/s (when using 60-ns 16-bit data path DRAM)
- Transfer rate: 8.33 MB/s (when using 70-ns 8-bit data path DRAM)
- Between 1 and 32 Mbits of DRAM can be used as buffer RAM.
- The user can freely set up the CD main channel and the C2 flags in buffer RAM.
- Built-in batch transfer function (function for transferring the CD main channel and the C2 flags in one operation)
- Built-in multiple transfer function (function for automatically transferring multiple blocks in a single operation)

#### Package Dimensions

unit: mm

3214-SQFP144



#### Specifications

##### Absolute Maximum Ratings at $V_{SS} = 0\text{ V}$

Parameter	Symbol	Conditions	Ratings	Unit
Maximum supply voltage	$V_{DD\text{ max}}$	$T_a = 25^\circ\text{C}$	-0.3 to +7.0	V
I/O voltages	$V_I, V_O$	$T_a = 25^\circ\text{C}$	-0.3 to $V_{DD} + 0.3$	V
Allowable power dissipation	$P_d\text{ max}$	$T_a \leq 70^\circ\text{C}$	550	mW
Operating temperature	$T_{opr}$		-30 to +70	$^\circ\text{C}$
Storage temperature	$T_{stg}$		-55 to +125	$^\circ\text{C}$
Soldering heat resistance (pins only)		10 seconds	235	$^\circ\text{C}$
Maximum I/O power	$I_I, I_O\text{ max}$		$\pm 20^*$	mA

Note: Per basic I/O cell.



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### Allowable Operating Ranges at Ta = -30 to +70°C, V<sub>SS</sub> = 0 V

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Supply voltage	V <sub>DD</sub>		4.5	5.0	5.5	V
Input voltage range	V <sub>IN</sub>		0		V <sub>DD</sub>	V

### DC Characteristics at Ta = -30 to +70°C, V<sub>SS</sub> = 0 V, V<sub>DD</sub> = 4.5 to 5.5 V

Parameter	Symbol	Applicable pins (see below)	Ratings			Unit
			min	typ	max	
Input high-level voltage	V <sub>IH1</sub>	TTL compatible: (1)	2.2			V
Input low-level voltage	V <sub>IL1</sub>	TTL compatible: (1)			0.8	V
Input high-level voltage	V <sub>IH2</sub>	TTL compatible, with pull-up resistor: (12)	2.2			V
Input low-level voltage	V <sub>IL2</sub>	TTL compatible, with pull-up resistor: (12)			0.8	V
Input high-level voltage	V <sub>IH3</sub>	TTL compatible, with pull-down resistor: (2)	2.2			V
Input low-level voltage	V <sub>IL3</sub>	TTL compatible, with pull-down resistor: (2)			0.8	V
Input high-level voltage	V <sub>IH4</sub>	TTL compatible, Schmitt characteristics: (3), (5), (13), (14)	2.5			V
Input low-level voltage	V <sub>IL4</sub>	TTL compatible, Schmitt characteristics: (3), (5), (13), (14)			0.6	V
Input high-level voltage	V <sub>IH5</sub>	CMOS compatible, Schmitt characteristics: (4)	0.8 V <sub>DD</sub>			V
Input low-level voltage	V <sub>IL5</sub>	CMOS compatible, Schmitt characteristics: (4)			0.2 V <sub>DD</sub>	V
Output high-level voltage	V <sub>OH1</sub>	I <sub>OH</sub> = -2 mA : (7), (10), (12)	V <sub>DD</sub> - 2.1			V
Output low-level voltage	V <sub>OL1</sub>	I <sub>OL</sub> = 2 mA : (7), (10), (12)			0.4	V
Output high-level voltage	V <sub>OH2</sub>	I <sub>OH</sub> = -8 mA : (6)	V <sub>DD</sub> - 2.1			V
Output low-level voltage	V <sub>OL2</sub>	I <sub>OL</sub> = 8 mA : (6)			0.4	V
Output high-level voltage	V <sub>OH3</sub>	I <sub>OH</sub> = -4 mA : (8), (13)	V <sub>DD</sub> - 2.1			V
Output low-level voltage	V <sub>OL3</sub>	I <sub>OL</sub> = 24 mA : (8), (13)			0.4	V
Output high-level voltage	V <sub>OH4</sub>	I <sub>OL</sub> = 24 mA : (9), (14)			0.4	V
Output low-level voltage	V <sub>OL5</sub>	I <sub>OL</sub> = 2 mA : (11)			0.4	V
Input leakage current	I <sub>IL</sub>	V <sub>I</sub> = V <sub>SS</sub> , V <sub>DD</sub> : (1), (2), (3), (4), (5), (12), (13), (14)	-10		+10	μA
Output leakage current	I <sub>OZ</sub>	When the output is high impedance: (9), (11), (13), (14)	-10		+10	μA
Pull-up resistance	R <sub>UP</sub>	(12)	40	80	160	kΩ
Pull-down resistance	R <sub>DN</sub>	(2)	40	80	160	kΩ

Note: The applicable pins are as follows:

#### INPUT

- (1) CSCTRL, RSSEL, HDB0 to 7, SUA0 to 6
- (2) TEST0 to 4
- (3) ZDMACK, ZHRST, ZRESET, BCK, C2PO, LRCK, SDATA, DA0 to 2, ZCS1FX, ZCS3FX
- (4) ZCS, ZRD, ZWR
- (5) ZDIOR, ZDIOW, DRESP, WFCK, SCOR

#### OUTPUT

- (6) MCK, MCK2
- (7) ZINT0, ZINT1
- (8) DMARQ, HINTRQ
- (9) IORDY, ZIOCS16
- (10) RA0 to 9, ZCAS0 to 1, ZRAS0 to 1, ZLWE, ZUWE, ZOE, DREQ
- (11) ZRSTCPU, ZRSTIC, ZSWAIT

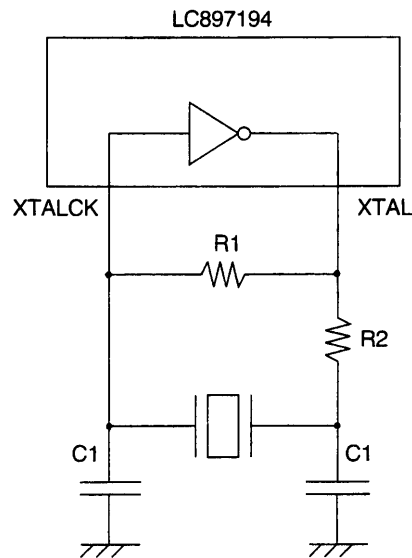
#### INOUT

- (12) D0 to 7, IO0 to 15
- (13) DD0 to 15
- (14) ZDASP, ZPDIAG

\*: The DC characteristics do not apply to the XTAL and XTALCK pins.

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### Recommended Oscillator Circuit Example



A06532

R1 = 120 k $\Omega$

R2 = 47  $\Omega$

C1 = 30 pF

With a crystal with a resonant frequency of 16.9344 MHz, or:

R1 = 3.3 k $\Omega$

R2 = None

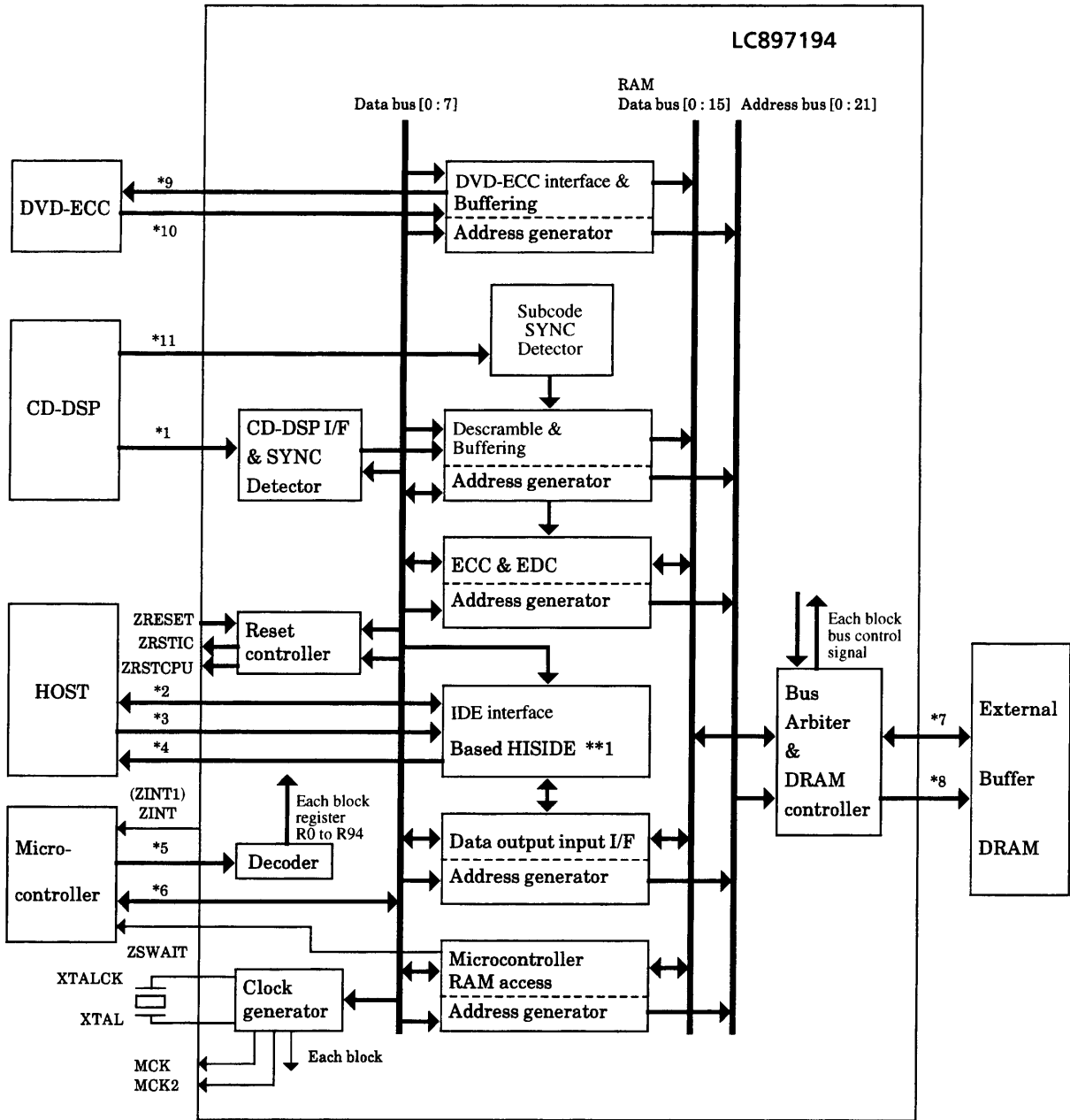
C1 = 5 pF

With a crystal with a resonant frequency of 33.8688 MHz.

If third harmonics are a problem in the 33.8688-MHz recommended circuit, consult with the manufacturer of the crystal for exact component values, since those values will be influenced by the printed circuit board used.

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Block Diagram



- \*1 BCK, SDATA, LRCK, C2PO
- \*2 DD0 to DD15, ZDASP, ZPDIAG
- \*3 ZCS1FX, ZCS3FX, DA0 to DA2, ZDIOR, ZDIOW, ZDMACK
- \*4 DMARQ, HINTRQ, ZIOCS16, IORDY, ZHRST
- \*5 ZRD, ZWR, SUA0 to SUA6, ZCS, CSCTRL
- \*6 D0 to D7
- \*7 IO0 to IO15
- \*8 RA0 to RA9, ZRAS0, ZRAS1, ZCAS0, ZCAS1, ZOE, ZUWE, ZLWE
- \*9 DREQ
- \*10 HDB0 to HDB7, DRESP
- \*11 WFCK, SCOR
- \*\*1 HISIDE (WD25C32) is made by WESTERN DIGITAL.

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### Pin Functions

typ					
I	Input	B	Bidirection	NC	Not connected
O	Output	P	Power		

Pin No.	Symbol	Type	Function
1	V <sub>SS0</sub>	P	
2	ZRAS0	O	RAS signal output 0 to the buffer DRAM (Output 0 is normally used.)
3	ZRAS1	O	RAS signal output 1 to the buffer DRAM
4	V <sub>SS0</sub>	P	
5	ZCAS0	O	CAS signal output 0 to the buffer DRAM (Output 0 is normally used.)
6	ZCAS1	O	CAS signal output 1 to the buffer DRAM
7	V <sub>SS0</sub>	P	
8	ZOE	O	Buffer RAM output enable
9	ZUWE	O	Buffer RAM upper write enable
10	ZLWE	O	Buffer RAM lower write enable
11	RA0	O	RA0 to RA9 are used for the data buffer DRAM address.
12	RA1	O	
13	RA2	O	
14	RA3	O	
15	RA4	O	
16	RA5	O	
17	RA6	O	
18	V <sub>DD</sub>	P	
19	V <sub>SS0</sub>	P	
20	RA7	O	RA0 to RA9 are used for the data buffer DRAM address.
21	RA8	O	
22	RA9	O	
23	TEST0	NC	Used for testing. There should be no connections to these pins. These pins must be left open.
24	TEST1	NC	
25	TEST2	NC	
26	TEST3	NC	
27	TEST4	NC	
28	IO0	B	Data I/O to/from data buffer DRAM Pull-up resistors are built in.
29	IO1	B	
30	IO2	B	
31	IO3	B	
32	IO4	B	
33	IO5	B	
34	IO6	B	
35	IO7	B	
36	V <sub>SS0</sub>	P	
37	V <sub>DD</sub>	P	

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Pin No.	Symbol	Type	Function
38	IO8	B	Data I/O to/from data buffer DRAM
39	IO9	B	Pull-up resistors are built in.
40	IO10	B	
41	IO11	B	
42	IO12	B	
43	IO13	B	
44	IO14	B	
45	IO15	B	
46	V <sub>SS0</sub>	P	
47	WFCK	I	Subcode input
48	SCOR	I	Subcode input
49	V <sub>SS0</sub>	P	
50	DREQ	O	DVD ECC data request output
51	DRESP	I	DVD ECC data latch signal input
52	HDB7	I	DVD ECC data input
53	HDB6	I	
54	V <sub>DD</sub>	P	
55	V <sub>SS0</sub>	P	
56	HDB5	I	DVD ECC data input
57	HDB4	I	
58	HDB3	I	
59	HDB2	I	
60	HDB1	I	
61	HDB0	I	
62	SDATA	I	Interface with the CD digital signal processor
63	BCK	I	
64	LRCK	I	
65	C2PO	I	
66	MCK2	O	Outputs the XTALCK signal times 1/1, 1/2, or 1/512, or stopped.
67	CSCTRL	I	Microcontroller chip select signal active high or low selection
68	RSSEL	I	Direct or indirect addressing selection
69	V <sub>SS0</sub>	P	
70	XTALCK	I	Crystal oscillator circuit input
71	XTAL	O	Crystal oscillator circuit output
72	V <sub>SS0</sub>	P	
73	V <sub>DD</sub>	P	
74	MCK	O	Outputs the XTALCK signal times 1/1 or 1/2, or stopped.
75	V <sub>SS0</sub>	P	
76	ZRSTIC	O	Reset output to the driver reset IC
77	ZRESET	I	LSI reset input
78	ZRD	I	Microcontroller data read signal input
79	ZWR	I	Microcontroller data write signal input
80	ZCS	I	Register chip select signal input from the microcontroller
81	ZINT1	O	ATAPI block interrupt output (selected by a register)
82	ZINT0	O	Interrupt request signal output to the microcontroller

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Pin No.	Symbol	Type	Function
83	SUA0	I	Microcontroller register selection signals The SUA0 pin functions as RS in indirect address mode.
84	SUA1	I	
85	SUA2	I	
86	SUA3	I	
87	SUA4	I	
88	SUA5	I	
89	SUA6	I	
90	V <sub>DD</sub>	P	
91	V <sub>SS0</sub>	P	
92	D0	B	Microcontroller data signals Pull-up resistors are built in.
93	D1	B	
94	D2	B	
95	D3	B	
96	D4	B	
97	D5	B	
98	D6	B	
99	D7	B	
100	V <sub>SS0</sub>	P	
101	ZRSTCPU	O	Reset signal output to the CPU
102	ZSWAIT	O	WAIT signal output to the microcontroller
103	ZHRST	I	ATAPI control signals
104	ZDASP	B	
105	ZCS3FX	I	
106	ZCS1FX	I	
107	DA2	I	
108	V <sub>SS0</sub>	P	
109	V <sub>DD</sub>	P	
110	DA0	I	ATAPI control signals
111	ZPDIAG	B	
112	DA1	I	
113	ZIOCS16	O	
114	HINTRQ	O	
115	ZDMACK	I	
116	V <sub>SS1</sub>	P	
117	IORDY	O	ATAPI control signals
118	ZDIOR	I	
119	ZDIOW	I	
120	DMARQ	O	
121	DD15	B	ATAPI data bus
122	V <sub>SS1</sub>	P	
123	DD0	B	ATAPI data bus
124	DD14	B	
125	DD1	B	

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Pin No.	Symbol	Type	Function
126	V <sub>DD</sub>	P	
127	V <sub>SS1</sub>	P	
128	DD13	B	ATAPI data bus
129	DD2	B	
130	DD12	B	
131	DD3	B	
132	V <sub>SS1</sub>	P	
133	DD11	B	ATAPI data bus
134	DD4	B	
135	DD10	B	
136	V <sub>SS1</sub>	P	
137	V <sub>DD</sub>	P	
138	DD5	B	ATAPI data bus
139	DD9	B	
140	DD6	B	
141	V <sub>SS1</sub>	P	
142	DD8	B	ATAPI data bus
143	DD7	B	
144	V <sub>DD</sub>	P	

NC pins must be left open. Make no connections to these pins.

Pin symbols that start with the letter Z are negative logic signals.

V<sub>SS0</sub> is the logic system ground and V<sub>SS1</sub> is the IDE interface driver ground.



## Pin Descriptions

### 1. ATAPI Pins

ZCS1FX (input)

Chip select signal used to select the command block register.

ZCS3FX (input)

Chip select signal used to select the control block register.

DA0 to DA2 (input)

Address used to access the ATAPI registers.

ZDASP(input/output)

Drive 1 is output, drive 0 is input.

Signal used to indicate to drive 0 that drive 1 exists. An external pull-up resistor must be provided.

DD0 to DD15 (input/output)

Data bus with a width of 16 bits. Data can be transferred in 8-bit and 16-bit units.

ZDIOR (input)

Read strobe signal from the host.

ZDIOW (input)

Write strobe signal from the host.

ZDMACK (input)

Acknowledge signal from the host in response to a drive DMARQ request signal during DMA transfers.

There is no internal pull-up resistor in the pin circuit.

DMARQ (output)

Drive request signal during DMA transfers.

HINTRQ (output)

Drive interrupt signal sent to the host.

ZIOCS16 (output)

This signal is asserted by the drive when the drive can support 16-bit transfers.

This signal is not asserted during DMA transfers.

IORDY (output)

Signal that indicates that the drive has completed response preparation during data transfers.

This signal will be low when preparation has not completed.

ZPDIAG (input/output)

Signal asserted by drive 1 to inform drive 0 that the diagnostics have completed. An external pull-up resistor must be provided.

ZHRST (input)

Reset signal from the host.

There is no internal pull-up resistor in the pin circuit.

### 2. Microcontroller Interface Pins

ZCS (input)

Chip select signal from the microcontroller.

CSCTRL (input)

Signal that selects the logic of the chip select from the microcontroller.

High - The ZCS signal functions as an active-low signal.

Low - The ZCS signal functions as an active-high signal.

ZRD, ZWR, SUA0 to SUA6 (input)

Microcontroller interface control pins. The SUA0 to SUA6 pins are used for addressing.

SUA0 functions as RS (the register select pin) in indirect addressing.

When SUA0 is low, and address read or write operation is performed, and when high, a data read or write operation is performed.

RSSEL (input)

Signal that selects direct or indirect addressing.

High - Indirect addressing selected.

Low - Direct addressing selected.

ZSWAIT (output)

When the microcontroller is accessing RAM, the sub-CPU must wait when this pin is low.

D7 to D0 (input/output)

Microcontroller data bus. Pull-up resistors are built in.

ZINT0 (output)

Interrupt request signal to the microcontroller.

The active level (high or low) can be changed by setting a register. The default setting is active low.

ZINT1 (output)

Interrupt request signal from the IDE block to the microcontroller.

3. Buffer RAM Pins

IO0 to IO15 (input/output)

Data bus for the buffer DRAM. Pull-up resistors are built in.

RA0 to RA9 (output)

Buffer RAM address pins.

ZRAS0, ZRAS1 (ZCS0, ZCS1) (output)

Buffer DRAM RAS output pins. Although ZRAS0 is used normally, in applications that use two 1M (64K × 16 bits) DRAMs, the ZRAS0 and ZRAS1 signals can be connected to each of DRAM RAS pins.

ZCAS0, ZCAS1 (output)

Buffer DRAM CAS output pins. Although ZCAS0 is used normally, in applications that use two-CAS DRAMs, the ZCAS0 can be connected to the DRAM UCAS pin, and ZCAS1 to the DRAM LCAS pin.

ZOE (output)

The buffer DRAM read output pin.

ZUWE, ZLWE (output)

Buffer DRAM write output signals. Connect these pins to the corresponding pins on the DRAMs.

When two-CAS DRAMs are used, connect ZLWE to the write enable signal.

4. Subcode Interface Pins

WFCK, SCOR (input)

Subcode interface pins. By connecting these pins to the CD DSP, the subcode sync can be detected and the CD main channel buffering can be started according to that sync. Subcode data buffering and ECC are not performed.

5. CD DSP Data Pins

BCK, SDATA, LRCK, C2PO (input)

Connect these pins to the CD DSP to acquire the CD-ROM data.

C2PO is the C2 flag pin.

6. DVD ECC interface pins

DRESP (input)

DVD ECC data is latched on the falling edge of this signal.

HDB0 to HDB7 (input)

DVD ECC data input pins.

DREQ (output)

DVD ECC data request output.

7. Other Pins

ZRESET (input)

The LC897194 reset pin. The LSI is reset when a low level is applied.

Applications must hold this pin low for at least 1 μs when power is first applied.

XTALCK, XTAL

These pins drive an external crystal at either 16.9344 MHz or 33.8688 MHz.

An external clock frequency can also be input to the XTALCK pin.

MCK (output)

Outputs either the XTALCK frequency or that frequency divided by 2. This output can be stopped.

MCK2 (output)

Outputs either the XTALCK frequency or that frequency divided by 2 (with the opposite phase of the MCK pin) or the XTALCK frequency divided by 512. This output can be stopped.

ZRSTIC (output)

This pin can be set to output a low level by either setting bit 7 in the microcontroller register R46 (ZSYSRES) low (0), or setting the ZHRST pin (pin 103) low. This pin output is in the high-impedance state when both ZSYSRES and ZHRST are high.

Since this pin has an open-drain circuit, an external pull-up resistor must be provided.

ZRSTCPU (output)

A low-going pulse of about 1 ms (when XTALCK = 34 MHz, or about 2 ms when XTALCK = 16 MHz) is generated on this pin when an ATAPI soft reset command (08H) is received.

An interrupt is issued to the microcontroller at this time. If the ZRESET pin (pin 77) is functioning with active-low logic, the ZRESET signal is output without change to ZRSTCPU.

Since this pin has an open-drain circuit, an external pull-up resistor must be provided.

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